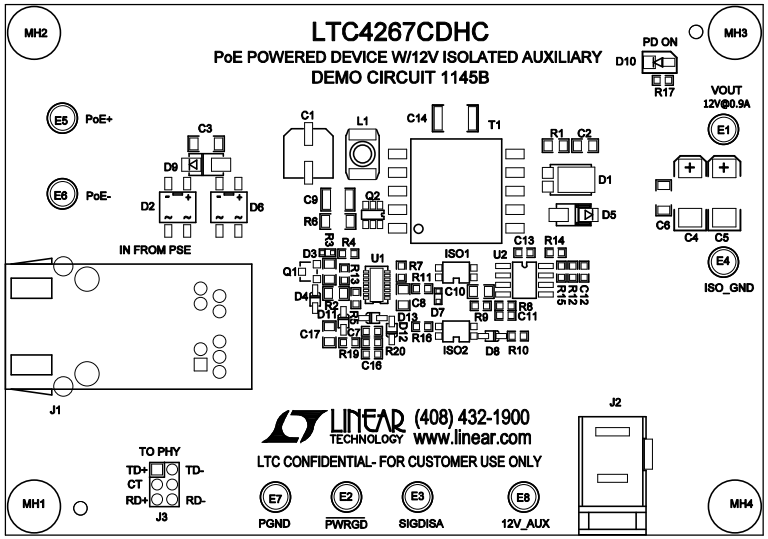
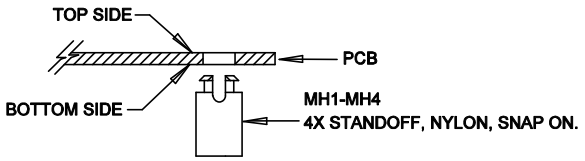
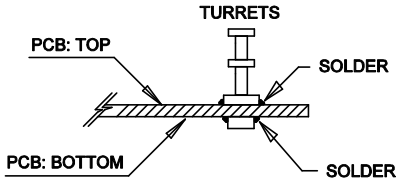
REVISION HISTORY				
ECO	REV	DESCRIPTION	APP. ENG.	DATE
1	1	REBUILD WITH CHANGES	KAUNG H.	06-16-11



NOTES: UNLESS OTHERWISE SPECIFIED

1. WORKMANSHIP SHALL BE IN ACCORDANCE WITH IPC-A-610.
2. ASSEMBLY PROCESS SHALL INCLUDE: REFLOW SOLDER TOP SIDE SMD. MAXIMUM SOLDER TEMPERATURE IS 240 C.
3. PARTS TO OMIT WILL BE SPECIFIED ON THE BILL OF MATERIALS. LOCATIONS OF OMITTED PARTS SHALL BE FREE OF SOLDER. MASK THE SOLDER STENCIL WHERE SMT PARTS ARE OMITTED.
4. DEPANELIZE BOARDS AFTER ASSEMBLY AND ROUTE-OUT THE BREAKOUT TABS ON FOUR SIDES OF THE BOARD EDGE.
6. DO NOT APPLY ANY KIND OF ASSEMBLY STAMP OR QA STAMP TO ANY BOARD.
7. INSTALL 4 STANDOFFS AT 4 LOCATIONS AS SHOWN BELOW:





APPROVALS	
PCB DES.	RB
APP ENG.	KAUNG H.
SCALE = NONE	

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TITLE: TOP ASSEMBLY DRAWING

PoE POWERED DEVICE W/12V ISOLATED AUXILIARY

SIZE	IC NO.	REV.
N/A	LTC4267CDHC DEMO CIRCUIT 1145B	1

FILENAME: DC1145B-1.PCB